

### **MAX9643**

### 60V High-Speed Precision Current-Sense Amplifier

#### **General Description**

The MAX9643 is a high-speed 60V precision unidirectional current-sense amplifier ideal for a wide variety of power-supply control applications. Its high signal bandwidth allows its use within DC-DC switching converter power-supply control loops with minimal phase delay.

The IC also features 50µV (max) precision input offset voltage, allowing small sense resistors to be used in applications where efficiency is important and when wide dynamic-range current measurement is needed.

High DC CMRR and AC CMRR make it easy to use in a wide variety of aggressive environments. The device is available in fixed gains of 2.5V/V and 10V/V. It is also available in a small, 8-pin TDFN (2mm x 3mm) package and is rated over the -40°C to +125°C temperature range.

### **Applications**

Industrial and Automotive Power Supplies **GSM** Base Station Power Supply High-Brightness LED Control Automotive Engine Control H-Bridge Motor Control

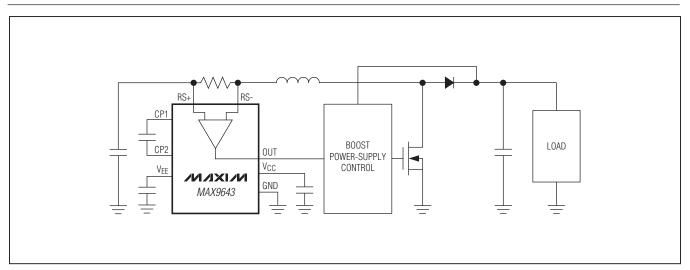
#### **Benefits and Features**

- ♦ Supports High-Voltage Applications ♦ Wide Input V<sub>CM</sub> = -1.5V to +60V
- **♦ Delivers High-Speed Operation** ♦ 15MHz Bandwidth
- ♦ Increases System Accuracy  $\Rightarrow$  Precision Vos = 50 $\mu$ V (max)
- **♦** -40°C to +125°C Specified Temperature Range

#### Ordering Information appears at end of data sheet.

For related parts and recommended products to use with this part, refer to www.maxim-ic.com/MAX9643.related.

### **Typical Operating Circuit**



#### **ABSOLUTE MAXIMUM RATINGS**

RS+ to GND, RS- to GND (Note 1)3.5V to +65V RS+ to RS±15V V <sub>CC</sub> to GND0.3V to +40V	CP2 to GND
V <sub>CC</sub> > 4.5V	ESD on RS+, RS±4kV HBM
OUT to GND0.3V to +4.5V	ESD on All Other Pins±2kV HBM
V <sub>FF</sub> to GND+0.3V to -4.5V	Maximum Power Dissipation
CP1 to GND0.3V to +4.5V	TDFN-EP (derate 16.7mW/°C at +70°C)1333.3mW
$V_{CC} \le 4.5V$	Operating Temperature Range40°C to +125°C
OUT to GND0.3V to (V <sub>CC</sub> + 0.3V)	Junction Temperature+150°C
V <sub>EE</sub> to GND+0.3V to (-V <sub>CC</sub> + 0.3V)	Lead Temperature (10s, soldering)+300°C
CP1 to GND0.3V to (V <sub>CC</sub> + 0.3V)	Soldering Temperature (reflow)+260°C

Note 1: Voltages below -3.5V are allowed, as long as the input current is limited to 5mA by an external resistor.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

#### PACKAGE THERMAL CHARACTERISTICS (Note 2)

Junction-to-Ambient Thermal Resistance (θ<sub>JA</sub>)...... 60°C/W 

Note 2: Package thermal resistances were obtained using the method described in JEDEC specification JESD51-7, using a fourlayer board. For detailed information on package thermal considerations, refer to www.maxim-ic.com/thermal-tutorial.

#### **ELECTRICAL CHARACTERISTICS**

( $V_{CC} = 5V$ ,  $V_{RS+} = V_{RS-} = 12V$ ,  $T_A = -40^{\circ}C$  to  $+125^{\circ}C$ , unless otherwise noted.) (Note 3)

PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	UNITS
DC CHARACTERISTICS							
Input Common-Mode Voltage	\/ \/	$V_{SH}$ , $V_{RS}$ $V_{SENSE} \le 100 \text{mV}$ $V_{CC} < 5 \text{V}$ , guaranteed by CMRR test, 3.		-1.5		+60	V
Range	VRS+, VRS-			3.5 - V <sub>CC</sub>		60	
Input Offact Voltage (Notes 4, E)	\/	$T_A = +25^{\circ}C$			10	50	/
Input Offset Voltage (Notes 4, 5)	V <sub>OS</sub>	-40°C < T <sub>A</sub> <+125°C				400	400 µV
Common-Mode Rejection Ratio	CMRR	$-1.5V \le V_{CM} \le 60V, T$	$A = +25^{\circ}C$	120	130		dB
(Note 5)	Civinn	$-1.5V \le V_{CM} \le 60V, -40^{\circ}C \le T_{A} \le +125^{\circ}C$		110			T UB
CMRR vs. Frequency (Note 5)	AC CMRR	f = 100kHz			90		dB
11.0		$T_A = +25^{\circ}C$			35	60	
Input Bias Current	I <sub>RS+</sub> , I <sub>RS-</sub>	-40°C < T <sub>A</sub> < +125°C				60	μΑ
Input Bias Current, $V_{CC} = 0V$ , $V_{RS+} = V_{RS-} = 60V$	I <sub>RS+</sub> , I <sub>RS</sub>					25	μΑ
Innut Officet Current (Nete C)		$T_A = +25^{\circ}C$			0.02	0.15	μΑ
Input Offset Current (Note 6)	IRS+ - IRS-	$T_A = +25^{\circ}C$ -40°C < $T_A$ < +125°C				0.3	
	FS	V <sub>CM</sub> < 2V		100			
Maximum Sense Voltage Before Input Saturation		\/ > 2\/	MAX9643T	400			mV
Imput Gataration		V <sub>CM</sub> ≥ 2V MAX9643U		300			

### **ELECTRICAL CHARACTERISTICS\* (continued)**

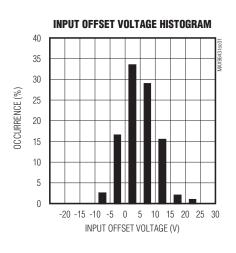
 $(V_{CC} = 5V, V_{RS+} = V_{RS-} = 12V, T_A = -40^{\circ}C \text{ to } +125^{\circ}C, \text{ unless otherwise noted.})$  (Note 3)

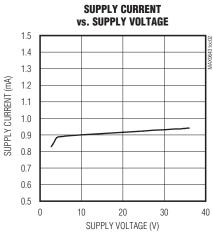
PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	
V II		MAX9643T		2.5		\(\O\)	
Voltage Gain (Note 4)		MAX9643U		10		V/V	
Valtage Coin Freez (Nata 4)	GE	$T_A = +25$ °C		0.06	0.5	%	
Voltage Gain Error (Note 4)	GE	-40°C < T <sub>A</sub> < +125°C			0.6		
AC CHARACTERISTICS							
Cianal Bandwidth	BW	$V_{SENSE} = 25 \text{mV}_{DC} + 2 \text{mV}_{P-P}, \text{MAX9643T}$		15		NAL I-	
Signal Bandwidth	DVV	$V_{SENSE} = 25 \text{mV}_{DC} + 2 \text{mV}_{P-P}, MAX9643U$		10		MHz	
Slew Rate	SR	$V_{OUT} = 10$ mV to 110mV		12		V/µs	
Delay from Output Saturation to V <sub>OL</sub>		V <sub>SENSE</sub> = 0 to 20mV		100		ns	
Delay from Input Saturation and Delay from Output Saturation to V <sub>OH</sub>		V <sub>SENSE</sub> = 10V to 10mV		1		μs	
OUTPUT CHARACTERISTICS							
Output Short-Circuit Current	I <sub>SC</sub>			3.39		mA	
		$I_{OUT} = 100 \mu A \text{ sink}, T_A = +25 ^{\circ} C$ 0.	0.2	1	- mV		
Output-Voltage Low (MAX9643T) (Note 5)	$I_{OUT} = 100 \mu A \text{ sink, } -40 ^{\circ}\text{C} < T_{A} < +125 ^{\circ}\text{C}$			1			
	VOL	$V_{OL}$ $I_{OUT} = 1$ mA sink, $T_A = +25$ °C 0.	0.6	10			
	IOU	$I_{OUT} = 1$ mA sink, -40°C < $T_A$ < +125°C			10	<u> </u>	
		$I_{OUT} = 100\mu A \text{ sink}, T_A = +25^{\circ} C$	$OUT = 100$ μA sink, $T_A = +25$ °C	0.5	3		
Output-Voltage Low (MAX9643U)	V <sub>OL</sub>	$I_{OUT} = 100 \mu A \text{ sink, } -40 ^{\circ}\text{C} < T_{A} < +125 ^{\circ}\text{C}$			3	mV	
(Note 5)		$I_{OUT} = 1$ mA sink, $T_A = +25$ °C		0.6	10		
		$I_{OUT} = 1$ mA sink, -40°C < $T_A$ < +125°C			10		
Output-Voltage High (Note 7)	V <sub>OH</sub>	I <sub>OUT</sub> = 1mA source, V <sub>CC</sub> < 4.5V	V <sub>CC</sub> - 1.3	3		V	
Output-voltage Flight (Note 1)	VOH	$I_{OUT} = 1$ mA source, $V_{CC} \ge 4.5$ V	3.2		2.3	V	
Capacitive Drive Capability	CL	R <sub>LOAD</sub> = Open, no sustained oscillation		30		pF	
POWER-SUPPLY CHARACTERIS	TICS						
Power Supply	V <sub>CC</sub>	Guaranteed by PSRR	2.7		36	V	
Power-Supply Rejection Ratio	PSRR	$V_{CC}$ = 2.7V to 36V, $V_{SENSE}$ = 10mV, $T_A$ = +25°C	107	125		dB	
(Note 5)		$-40^{\circ}\text{C} < \text{T}_{A} < +125^{\circ}\text{C}$	100				
Quiescent Supply Current	loo	$T_A = +25^{\circ}C$	1000 1400 1600		1400	μΑ	
Quiescent supply current	Icc	-40°C < T <sub>A</sub> < +125°C			μA		
Charge-Pump Current	I <sub>EE</sub>	$\Delta V_{EE} = 500 \text{mV}$		4		mA	

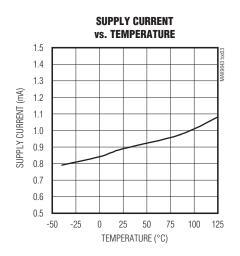
- Note 3: All devices are 100% production tested at  $T_A = +25$ °C. Temperature limits are guaranteed by design and/or characterization.
- Note 4: Gain and offset voltage are calculated based on two point measurements: V<sub>SENSE1</sub> = 10mV and V<sub>SENSE2</sub> = 100mV.
- Note 5: V<sub>OS</sub>, V<sub>OL</sub>, CMRR, and PSRR are measured with the charge pump off.
- Note 6: Guaranteed by design and/or characterization.
- Note 7: The maximum V<sub>SENSE</sub> of the MAX9643T is 400mV. With the gain = 2.5V/V, the output swing high is not applicable to the MAX9643T.

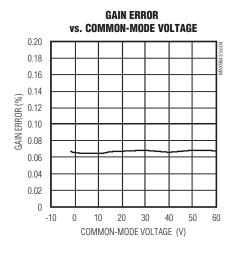
### **Typical Operating Characteristics**

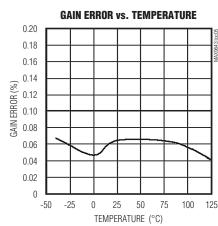
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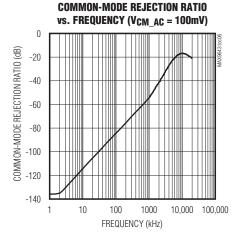






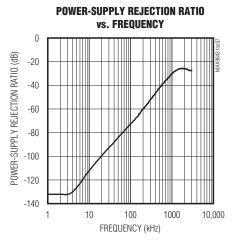


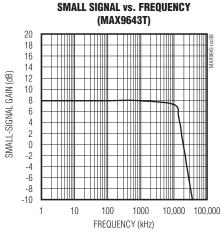


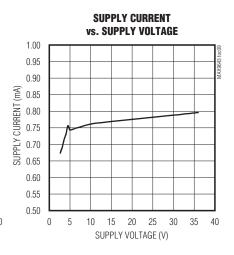


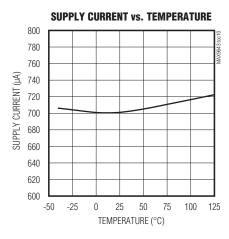
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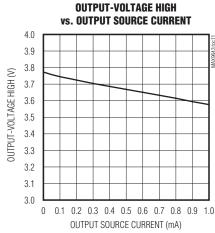
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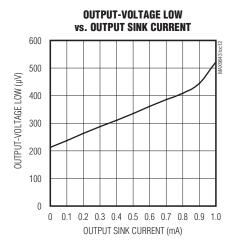






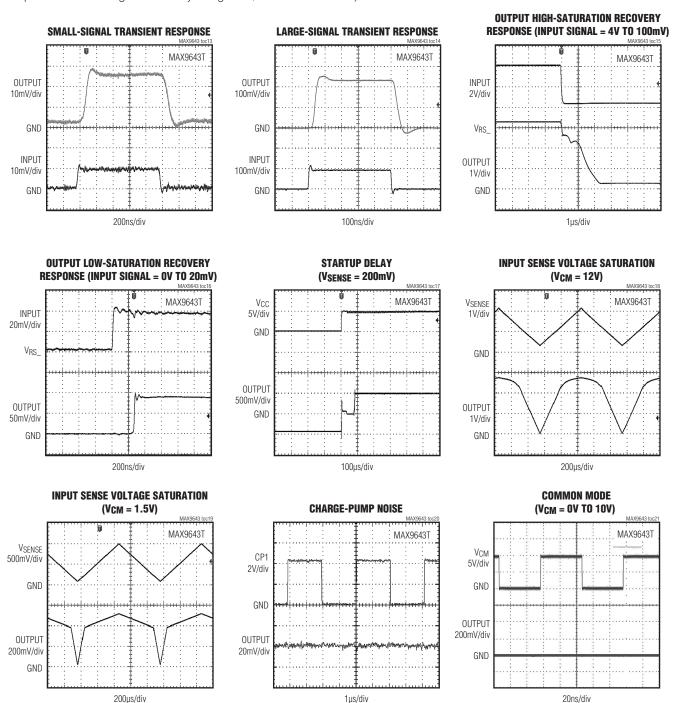






### **Typical Operating Characteristics (continued)**

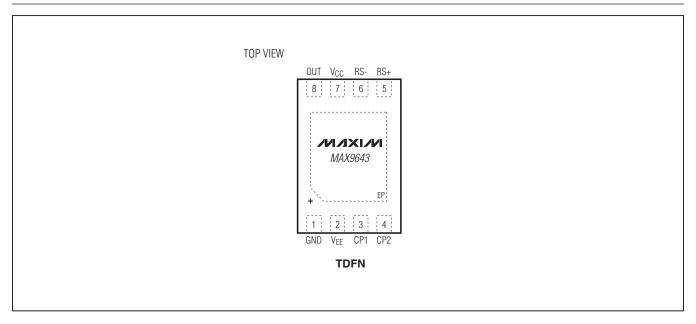
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### **MAX9643**

# **60V High-Speed Precision Current-Sense Amplifier**

### **Pin Configuration**



# **Pin Description**

PIN	NAME	DESCRIPTION			
1	GND	Ground			
2	V <sub>EE</sub>	Charge-Pump Output. Connect 1µF to GND.			
3	CP1	Positive Terminal of 1µF Flying Capacitor			
4	CP2	egative Terminal of 1µF Flying Capacitor			
5	RS+	Positive Sense Resistor Input			
6	RS-	Negative Sense Resistor Input			
7	V <sub>CC</sub>	Power Supply			
8	OUT	Output			
_	EP	Exposed Pad. Must be externally connected to GND.			

### **Detailed Description**

The MAX9643 is a high-speed precision current-sense amplifier ideal for a wide variety of high-performance industrial and automotive power-supply applications. The device's low input offset voltage, tight gain error, and low temperature drift characteristics allow the use of smallsense resistors for current measurements to improve power-supply conversion efficiency and accuracy of measurements. Its fast response allows it to react quickly to switching currents as is common in power-supply circuits, and makes it possible to be used as part of control loops.

The unidirectional high-side, current-sense amplifier also features a wide -1.5V to +60V input common-mode range. This feature allows monitoring of power-supply load current even if the rail is shorted to ground. Highside current monitoring does not interfere with the ground path of the load being measured, making the IC particularly useful in a wide range of high-reliability systems.

The IC has been designed on a proprietary high-speed complementary BiCMOS SOI process. This high-voltage analog process is optimized for excellent AC dynamic performance, ultra-low noise, wide operating voltage range, and low-drift signal conditioning circuitry.

### **Application Information**

#### Internal Charge Pump

An internal charge pump on the part is utilized to provide two attractive application features:

- Input common-mode voltage range extends to 1.5V below ground.
- Output voltage range extends down to true ground.

A 250kHz internal charge pump is used to generate a negative voltage rail to bias both the input stage and output stage of the current-sense amplifier. Use a 1µF ceramic capacitor between the CP1 and CP2 pins of the IC, and ensure a tight layout to minimize loop area. Using a 1µF ceramic capacitor from VEE to GND is essential to good low-noise performance.

It is possible to also connect the VEE pin directly to an external -5V power supply. Ensure that this voltage is lower than the internally generated charge-pump voltage.

The MAX9643 EV kit shows a good example layout. A representation is shown in Figure 1.

#### Input Common-Mode Voltage Range

The use of an internal negative voltage rail for its input stage allows the current-sense amplifier to extend its input common-mode voltage below ground without any crossover inaccuracies. Crossover problems with precision can occur with alternate architectures of current-sense amplifiers that use two different input differential stages to cover the entire operating commonmode voltage range (either npn/pnp transistors or pnp transistor and resistor-based input stages).

The minimum input common-mode voltage capability is dependent on the internal negative voltage rail generated by the charge pump. Since this negative voltage rail goes down at low values of VCC (i.e., when under 5V), the minimum input common-mode voltage rail is also limited at low VCC.

The negative input common-mode voltage specification can be exceeded if the input current is limited to under 5mA. This is typically accomplished by using series input resistors. The input ESD structure for negative input common-mode voltages looks like 5 series-connected diodes. Assuming an on-drop of 0.7V per diode, negative

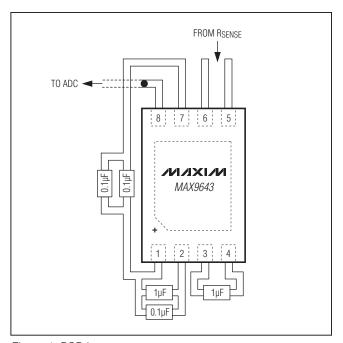


Figure 1. PCB Layout

input voltage transients below -3.5V should be limited by the use of input series resistors. For example, if an input voltage transient or fault condition of -12V were to occur in the application, use a resistor greater than 8.5V/5mA = 1700 $\Omega$ . Use  $2k\Omega$  for margin.

The maximum input common-mode voltage extends up to 60V over the entire VCC range of 2.7V to 36V. It is recommended to shield the device from overvoltages above its 65V absolute maximum rating to protect the device.

#### **Output Voltage Range**

The internal negative voltage rail generated by the charge pump is also used to bias the output stage of the current-sense amplifier, allowing it to feature true VOI = 0V performance. This feature allows small sense voltages to be used and eases interface to other analog and mixed-signal ICs. In reality, attaining true VOL = 0V specification is usually limited by the offset voltage of the current-sense amplifier since Vout = Vos x gain, when input VSENSE = 0V.

In addition, the maximum output voltage of the IC is internally clamped to less than 5V even when it is powered from a 40V rail. This allows easy interface to low-voltage downstream circuitry without worrying about protecting them from large input voltage transients or faults.

#### **Choosing the Sense Resistor**

Choose RSENSE based on the following criteria:

- Voltage loss: A high RSENSE value causes the power-source voltage to reduce due to IR drop. For minimal voltage loss, use the lowest RSENSE value.
- **Accuracy:** A high RSENSE value allows lower currents to be measured more accurately. This is because input offset voltages become less significant when the sense voltage is larger.

- Efficiency and power dissipation: At high current levels, the I<sup>2</sup>R losses in RSENSE can be significant. Take this into consideration when choosing the resistor value and its power dissipation (wattage) rating. Also, the sense resistor's value might drift if it is allowed to heat up excessively.
- Inductance: Keep inductance low if ISENSE has a large high-frequency component. Because of the high currents that flow through RSENSE, take care to eliminate parasitic trace resistance from causing errors in the sense voltage. Either use a four-terminal current-sense resistor or use Kelvin (force and sense) PCB layout techniques.

#### **Power-Supply Bypassing and Grounding**

For most applications, bypass VCC to GND with a 0.1µF ceramic capacitor. In many applications, VCC can be connected to one of the current monitor terminals (RS+ or Rs-). Because VCC is independent of the monitored voltage, VCC can be connected to a separate regulated supply. There are no specific power-supply sequencing issues to consider. The part can withstand 60V input common-mode voltages even when VCC = 0V, and maintains a high input impedance in this application condition.

#### **Chip Information**

PROCESS: BICMOS

### **Ordering Information**

PART	PIN- PACKAGE	GAIN (V/V)	TEMP RANGE
MAX9643TATA+	8 TDFN-EP*	2.5	-40°C to +125°C
MAX9643UATA+	8 TDFN-EP*	10	-40°C to +125°C

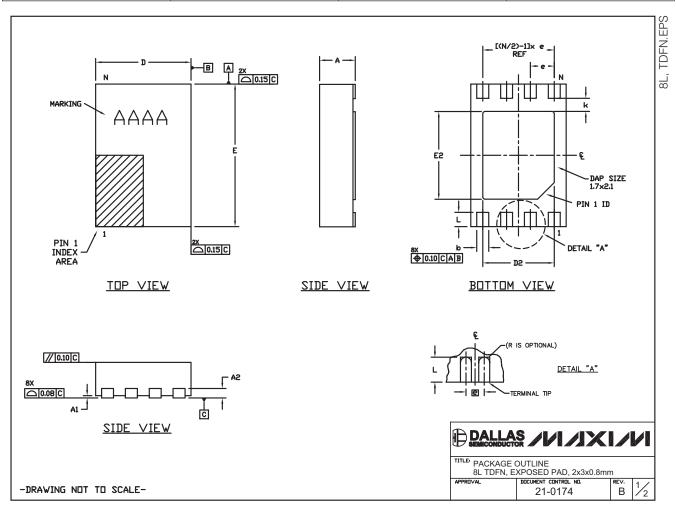
<sup>+</sup>Denotes a lead(Pb)-free/RoHS-compliant package.

<sup>\*</sup>EP = Exposed pad.

### **Package Information**

For the latest package outline information and land patterns (footprints), go to www.maxim-ic.com/packages. Note that a "+", "#", or "-" in the package code indicates RoHS status only. Package drawings may show a different suffix character, but the drawing pertains to the package regardless of RoHS status.

PACKAGE TYPE	PACKAGE CODE	OUTLINE NO.	LAND PATTERN NO.
8 TDFN-EP	T823+1	21-0174	90-0091



### Package Information (continued)

For the latest package outline information and land patterns (footprints), go to www.maxim-ic.com/packages. Note that a "+", "#", or "-" in the package code indicates RoHS status only. Package drawings may show a different suffix character, but the drawing pertains to the package regardless of RoHS status.

	DIMENSIONS				
SYMBOL	MIN.	MAX.			
Α	0.70	0.75	0.80		
E	2.95	3.00	3.05		
D	1.95	2.00	2.05		
A1	0.00	0.02	0.05		
L	0.30	0.40	0.50		
k	0.20 MIN.				
A2		0.20 REF.			
N	8				
е	0.50 BSC				
b	0.18 0.25 0.30				

	EXPOSED PAD PACKAGE					
PKG.		E2			D2	
CODE	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
T823-1	1.60	1.75	1.90	1.50	1.63	1.75

- 1. ALL DIMENSIONS ARE IN mm. ANGLES IN DEGREES.
  2. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.
  COPLANARITY SHALL NOT EXCEED 0.08mm.
  3. WARPAGE SHALL NOT EXCEED 0.10mm.

- 4. PACKAGE LENGTH/PACKAGE WIDTH ARE CONSIDERED AS SPECIAL CHARACTERISTIC(S).
- 5. COMPLY TO JEDEC MO229, TYPE 1, VERSION WCED-2.
- 6. "N" IS THE TOTAL NUMBER OF LEADS.
  7. NUMBER OF LEADS SHOWN ARE FOR REFERENCE ONLY.
  8. MARKING IS FOR PACKAGE ORIENTATION REFERENCE ONLY.
- 9. MATERIAL MUST COMPLY WITH BANNED AND RESTRICTED SUBSTANCES SPEC #10-0131.

DALLAS /// SEMCONDUCTOR /// TITLE PACKAGE OUTLINE 8L TDFN, EXPOSED PAD, 2x3x0.8mm DOCUMENT CONTROL NO. B 2/2 21-0174

-DRAWING NOT TO SCALE-

### **Revision History**

- 1	REVISION NUMBER	REVISION DATE	DESCRIPTION	PAGES CHANGED
	0	8/11	Initial release	_

Maxim cannot assume responsibility for use of any circuitry other than circuitry entirely embodied in a Maxim product. No circuit patent licenses are implied. Maxim reserves the right to change the circuitry and specifications without notice at any time.